PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT8143828

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
XIAOXIA ZHANG	11/22/2020
OZCAN OZTURK	12/08/2020
MOSTAFA KHOSHNEVISAN	11/20/2020
JING SUN	11/21/2020

RECEIVING PARTY DATA

Name:	QUALCOMM INCORPORATED	
Street Address:	5775 MOREHOUSE DRIVE	
City:	SAN DIEGO	
State/Country:	CALIFORNIA	
Postal Code:	92121-1714	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	18452415

CORRESPONDENCE DATA

Fax Number: (303)473-2720

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 3034732700

Email: eygondolo@hollandhart.com

Correspondent Name: HOLLAND & HART LLP/QUALCOMM

Address Line 1: P.O. BOX 11583

Address Line 4: SALT LAKE CITY, UTAH 84147

ATTORNEY DOCKET NUMBER: PR712.01.01*(103038.3189)	
NAME OF SUBMITTER:	J. SCOTT KARREN
SIGNATURE:	/J. Scott Karren/
DATE SIGNED:	08/31/2023

Total Attachments: 12

source=194685C1C1 Assignment#page1.tif source=194685C1C1 Assignment#page2.tif source=194685C1C1 Assignment#page3.tif

WHEREAS, WE,

- Xiaoxia ZHANG, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121-1714.
- Ozcan OZTURK, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121-1714.
- 3. Mostafa KHOSHNEVISAN, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121-1714.
- Jing SUN, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121-1714.

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to HANDLING MISSED HYBRID AUTOMATIC REPEAT REQUEST (HARQ) OPPORTUNITIES, OR BOTH FOR DISCONTINUOUS RECEPTION (DRX) (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged. WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No. 16/987,920 filed August 7, 2020, Qualcomm Reference No. 194685, and all provisional applications relating thereto, together with U.S. Provisional Application No. 62/891,242, filed August 23, 2019, Qualcomm Reference No. 194685P1, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof:

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument:

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance:

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

PATENT QUALCOMM Ref No. 194685 Page 3 of 3

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _	Sand Dreg Foo LOCATION	11/22/2020 DATE	Xiaoxia ZHANG
Done at _	LOCATION , On	DATE	Ozcan OZTURK
Done at _	LOCATION , on	DATE	Mostafa KHOSHNEVISAN
Done at_	LOCATION , OB	DATE	Jing SUN

WHEREAS, WE,

- 1. Xiaoxia ZHANG, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121-1714,
- 2. Ozcan OZTURK, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121-1714,
- 3. Mostafa KHOSHNEVISAN, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121-1714,
- 4. Jing SUN, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121-1714,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to HANDLING MISSED HYBRID AUTOMATIC REPEAT REQUEST (HARQ) OPPORTUNITIES, MULTIPLE HARQ OPPORTUNITIES, OR BOTH FOR DISCONTINUOUS RECEPTION (DRX) (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

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AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at_	, on		
	LOCATION	DATE	Xiaoxia ZHANG
Done at_	20 Diego, CA, on	12/8/2020	<u>Jan</u>
	LOCATION	DATE	Ozcan OZTURK
Done at	, 013		
	LOCATION	DATE	Mostafa KHOSHNEVISAN
Done at	, on		
	LOCATION	DATE	Jing SUN

WHEREAS, WE,

- 1. Xiaoxia ZHANG, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121-1714,
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Done at	, on		
	LOCATION	DATE	Xiaoxia ZHANG
Done at _	LOCATION , on _	DATE	Ozcan OZTURK
Done at _	San Oiego, cA, on _ LOCATION	11,20,2020 DATE	Mostafa KHOSHNEVISAN
Done at _	, on _	DATE	Jing SUN

WHEREAS, WE,

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Done at	, or	1	
_	LOCATION	DATE	Xiaoxia ZHANG
Done at _	, or		
	LOCATION	DATE	Ozcan OZTURK
Done at _	, or	1	
	LOCATION	DATE	Mostafa KHOSHNEVISAN
Done at	San Dieyo, (A) or	012211221)	20-
200 41	LOCATION	DATE	Jing SUN

RECORDED: 08/31/2023

PATENT

REEL: 064764 FRAME: 0169